SEMICONDUCTOR CHIP RESIN ENCAPSULATION METHOD

Abstract of the Disclosure

A semiconductor chip resin encapsulation method, including a resin filling and curing step of encapsulating a plurality of semiconductor chips, which have been bonded onto a substrate, in a molten resin, and curing the molten resin. The semiconductor chip resin encapsulation method further includes a grinding step of grinding an upper surface of the cured resin to decrease the thickness of the encapsulating resin to a predetermined value.

Figure 7